

PATENT ABSTRACTS OF JAPAN

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(21)Application number : 63-066709 (71)Applicant : SANSIN KAGAKU KOGYO KK
(22)Date of filing : 19.03.1988 (72)Inventor : YAMAMOTO YOSHINARI
AKASHI SUMIO

(54) COMPOSITION OF ETCHING SOLUTION FOR COPPER AND ETCHING METHOD

(57)Abstract:

PURPOSE: To prepare the compsn. of an etching soln. in which the lowering of etching speed by chloric ions is prevented by adding effective amounts of benzotriazole to an etching soln. contg. specific ratios of sulfuric acid and hydrogen peroxide.

CONSTITUTION: Benzotriazole and/or tolyltriazole, 100–5000ppm, is incorporated into an etching soln. contg. 5–25vol.% sulfuric acid and 3–20vol.% hydrogen peroxide to prepare the compsn. of an etching soln. for copper. By this method, the compsn. of the etching soln. for copper in which the deterioration caused by chloric ions is prevented without drastically lowering the etching speed even if hydrogen ions contained in city water are mingled can be obtd.

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